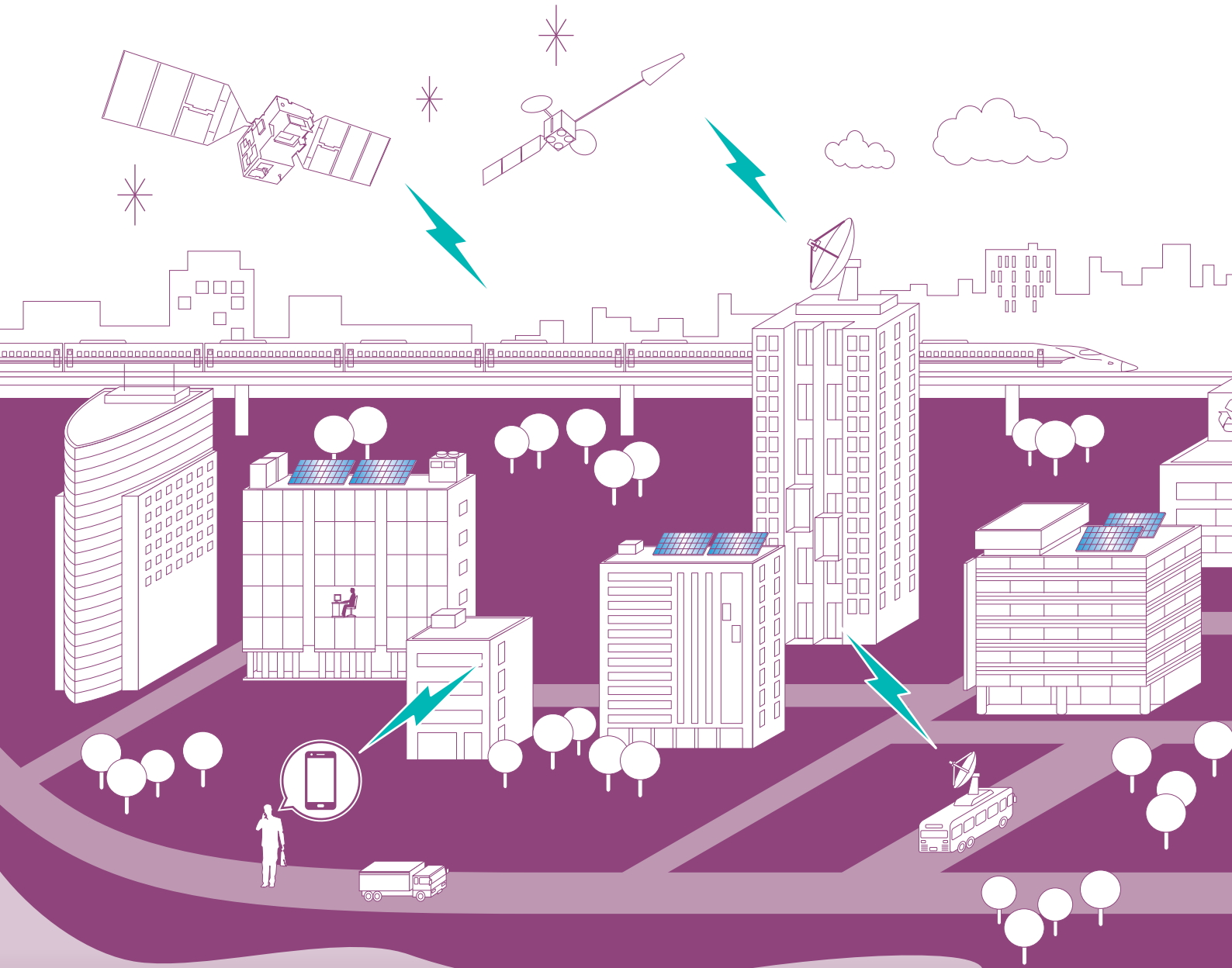
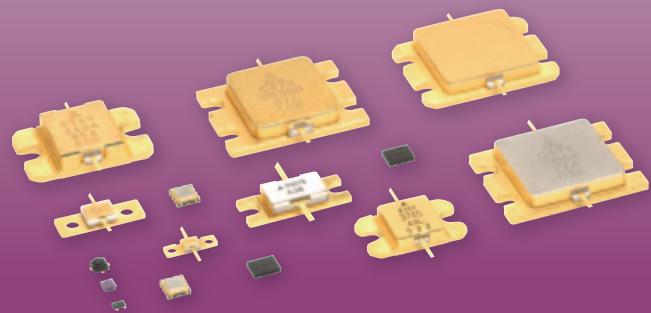


HIGH FREQUENCY DEVICES



High Frequency Devices



The Best Solution for Realizing the Information Era.

Communication networks, such as high speed Internet, video-on-demand and high-speed data communication, are developing rapidly. We are ready to offer the best solution to the systems for realizing the information era by providing a variety of GaAs/GaN products designed for satellite communication systems to base stations and cellular handset applications.

LINE UP

SELECTION MAP

PRODUCT LIST

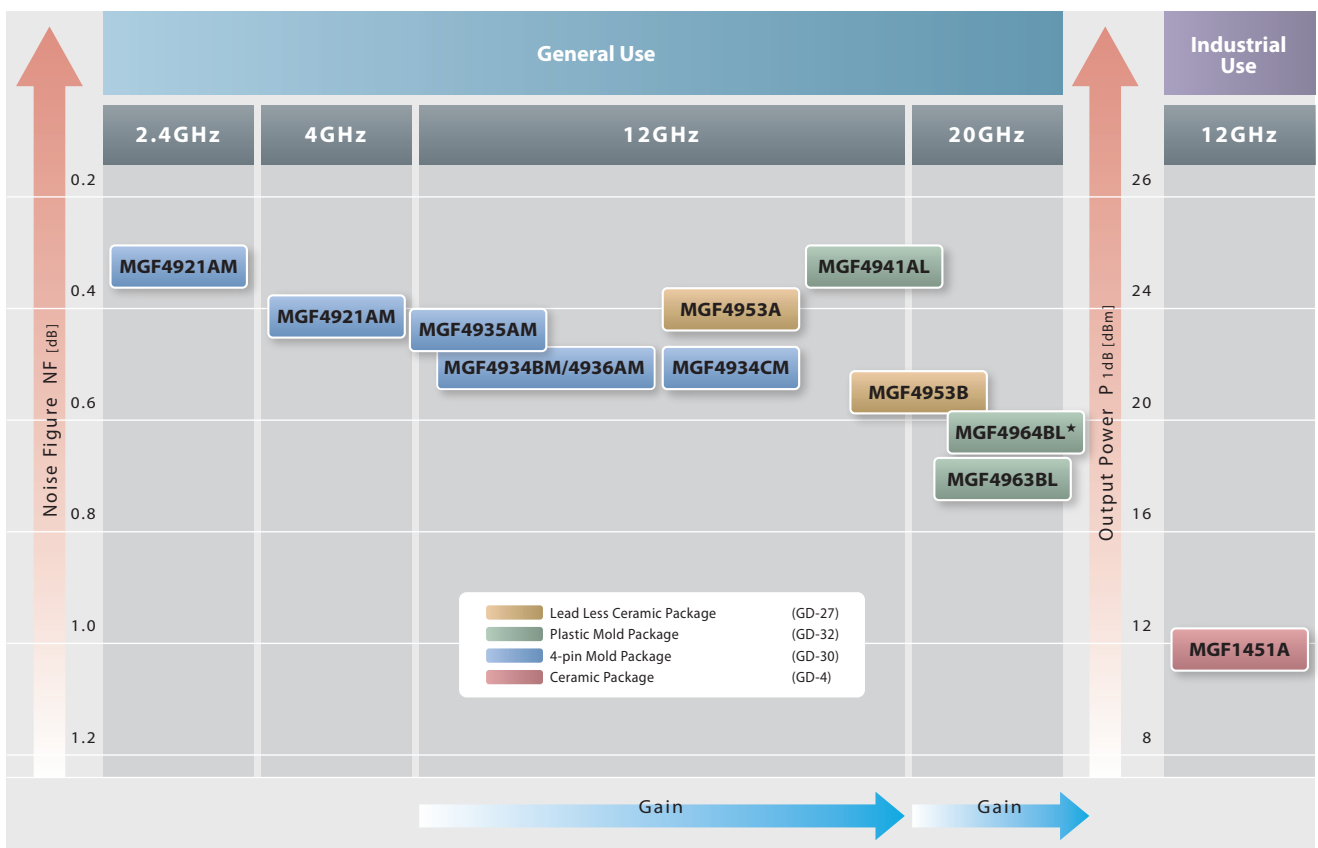
APPLICATION EXAMPLES

LINE UP

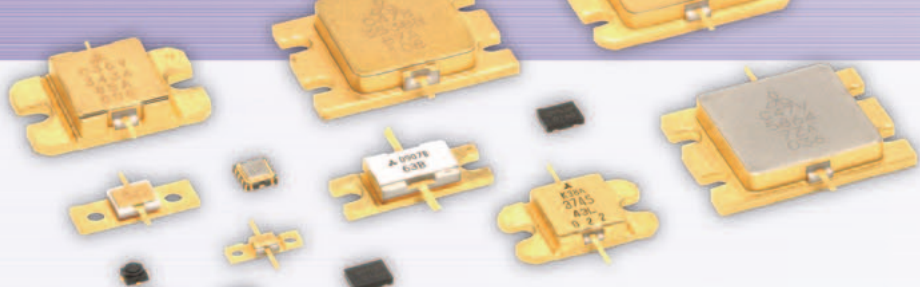
High Frequency Devices	For Communications	GaAs FET/HEMT Series for Microwave-band Low-Noise Amplifiers	MAP For SELECTION	PRODUCT LIST
			Page 1	Page 5
		GaAs FET/InGaP HBT Series for Microwave-band High Power Amplifiers (Discrete Devices)	Page 2	Page 5,6
		GaN HEMT Series for Microwave-band High Power Amplifiers	Page 2	Page 6
		Internally Matched GaAs FET Series for Microwave-band High Power Amplifiers	Page 3	Page 6,7
	For Mobile Terminal	GaAs Power Amplifiers for Mobile Phone and Data Communication	Page 3	Page 8
		GaAs Amplifiers for WiMAX / Wi-Fi	Page 4	Page 8

SELECTION MAP

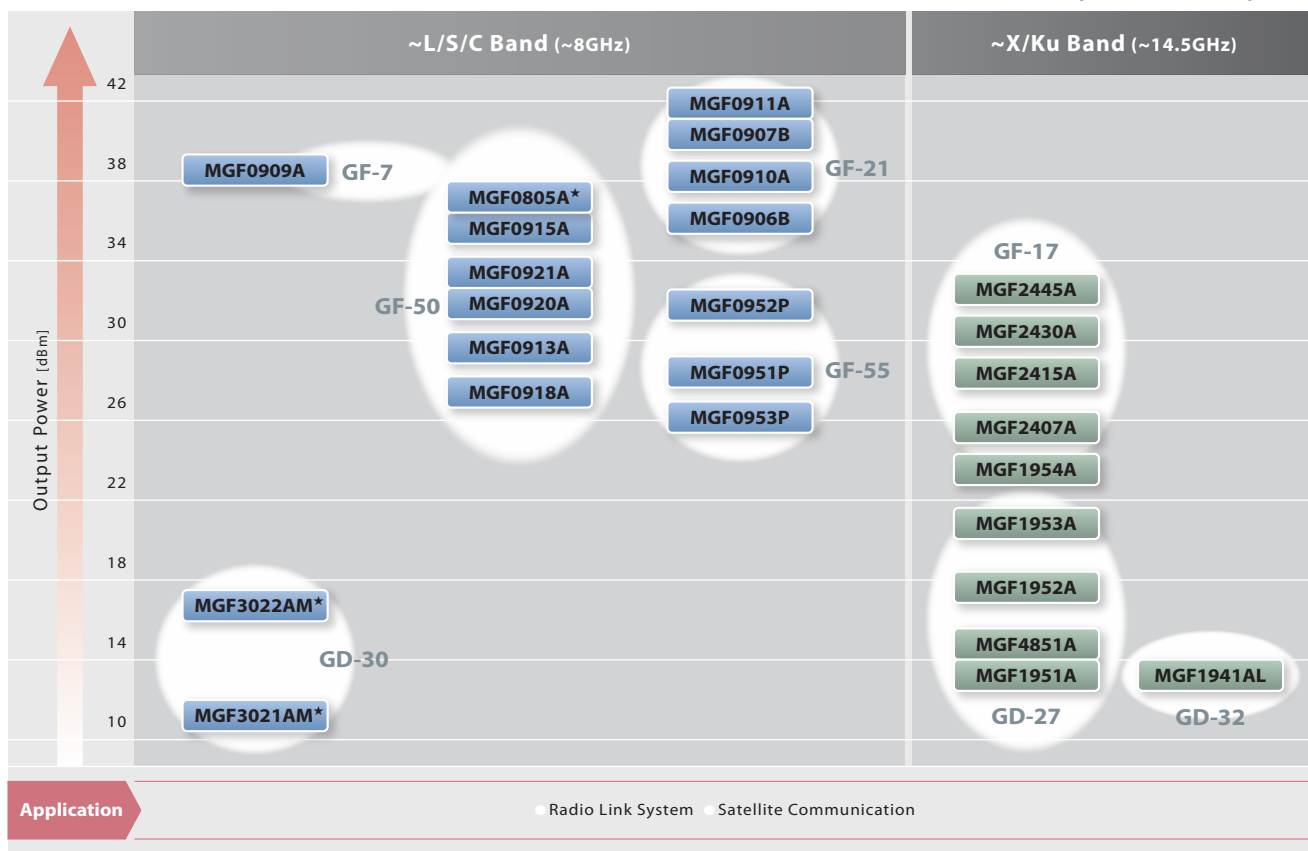
GaAs FET SERIES FOR MICROWAVE-BAND LOW-NOISE AMPLIFIERS



*: New Product

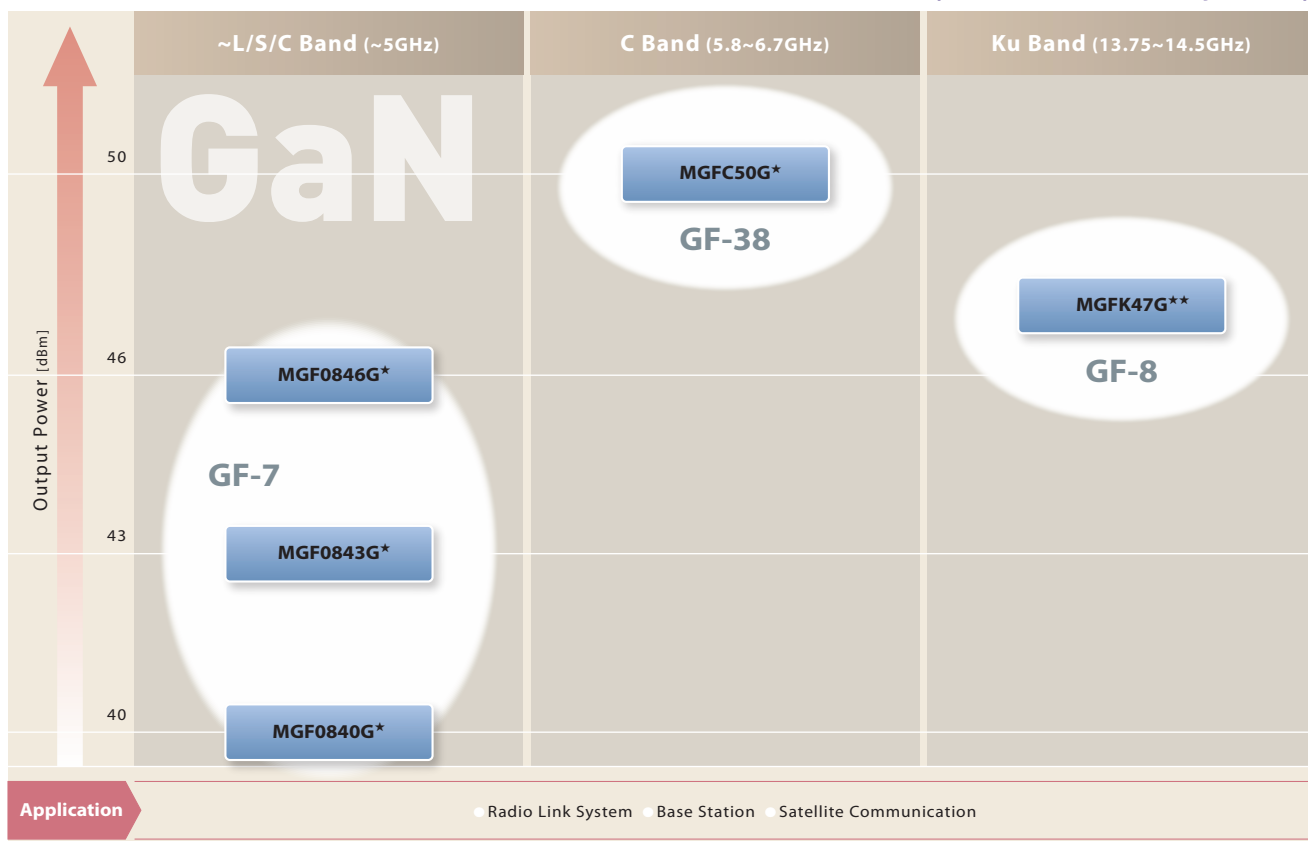


GaAs FET/InGaP HBT SERIES FOR MICROWAVE-BAND HIGH POWER AMPLIFIERS (Discrete Devices)



★: New Product

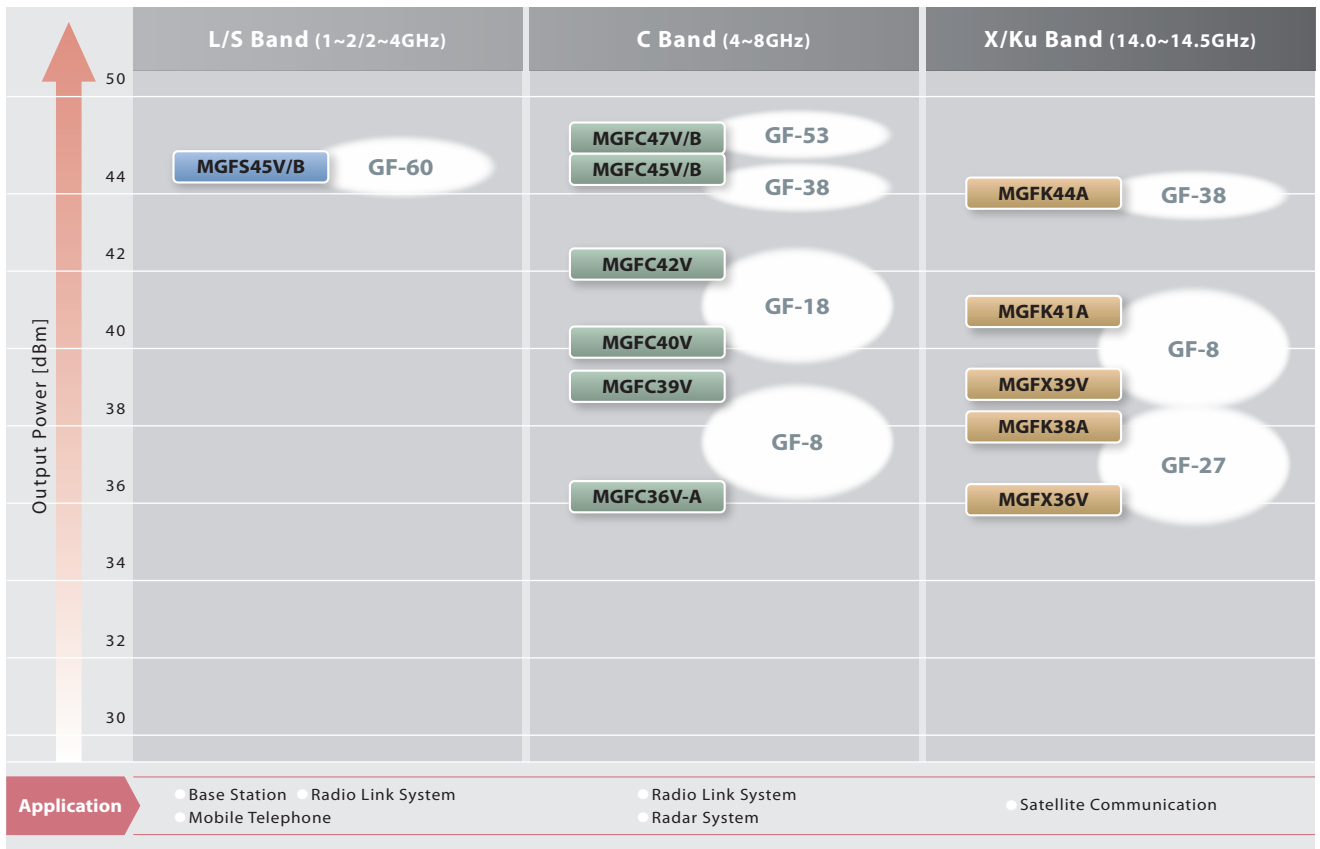
GaN HEMT SERIES FOR MICROWAVE-BAND HIGH POWER AMPLIFIERS (Discrete Devices / Internally Matched)



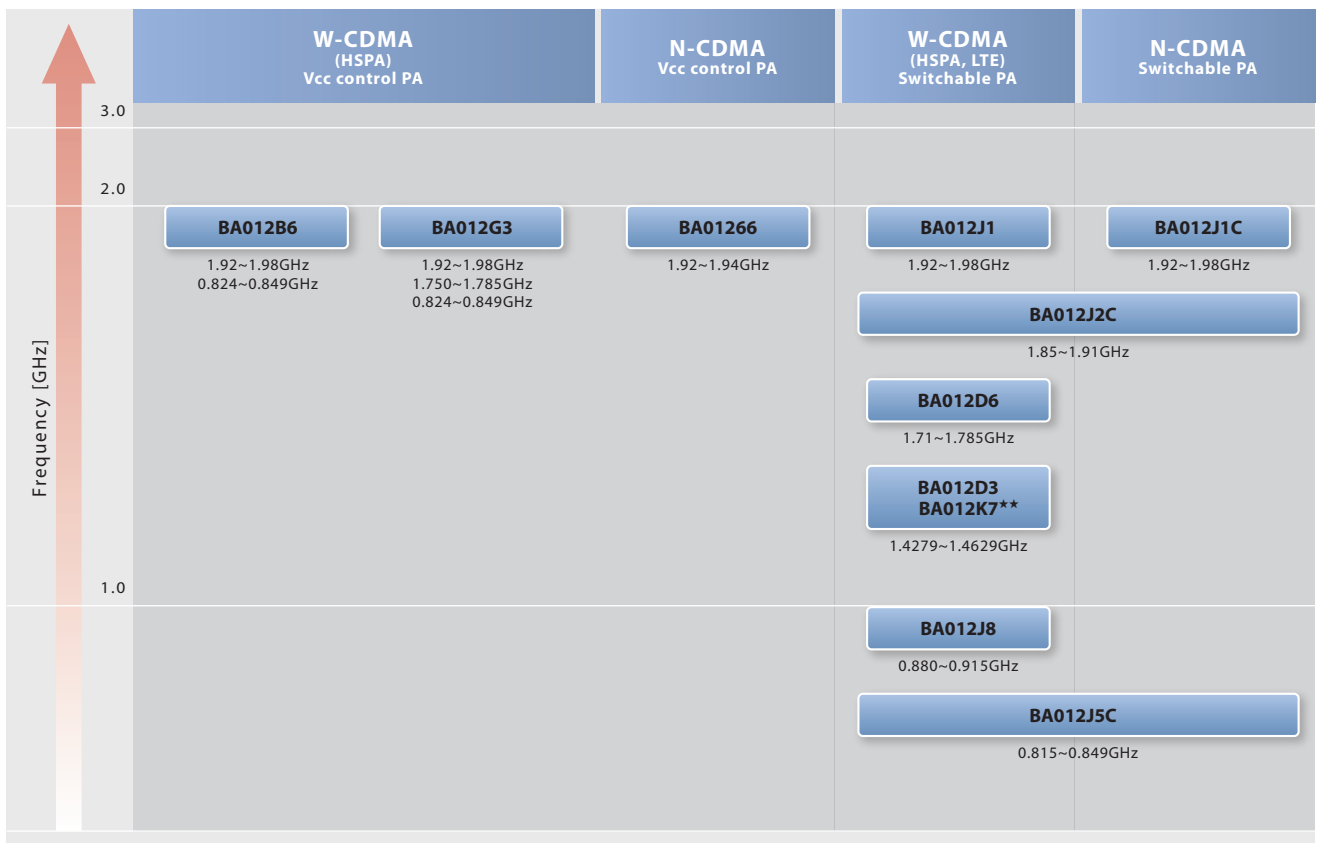
★: New Product ★★: Under Development

SELECTION MAP

INTERNALLY MATCHED GaAs FET SERIES FOR MICROWAVE-BAND HIGH POWER AMPLIFIERS



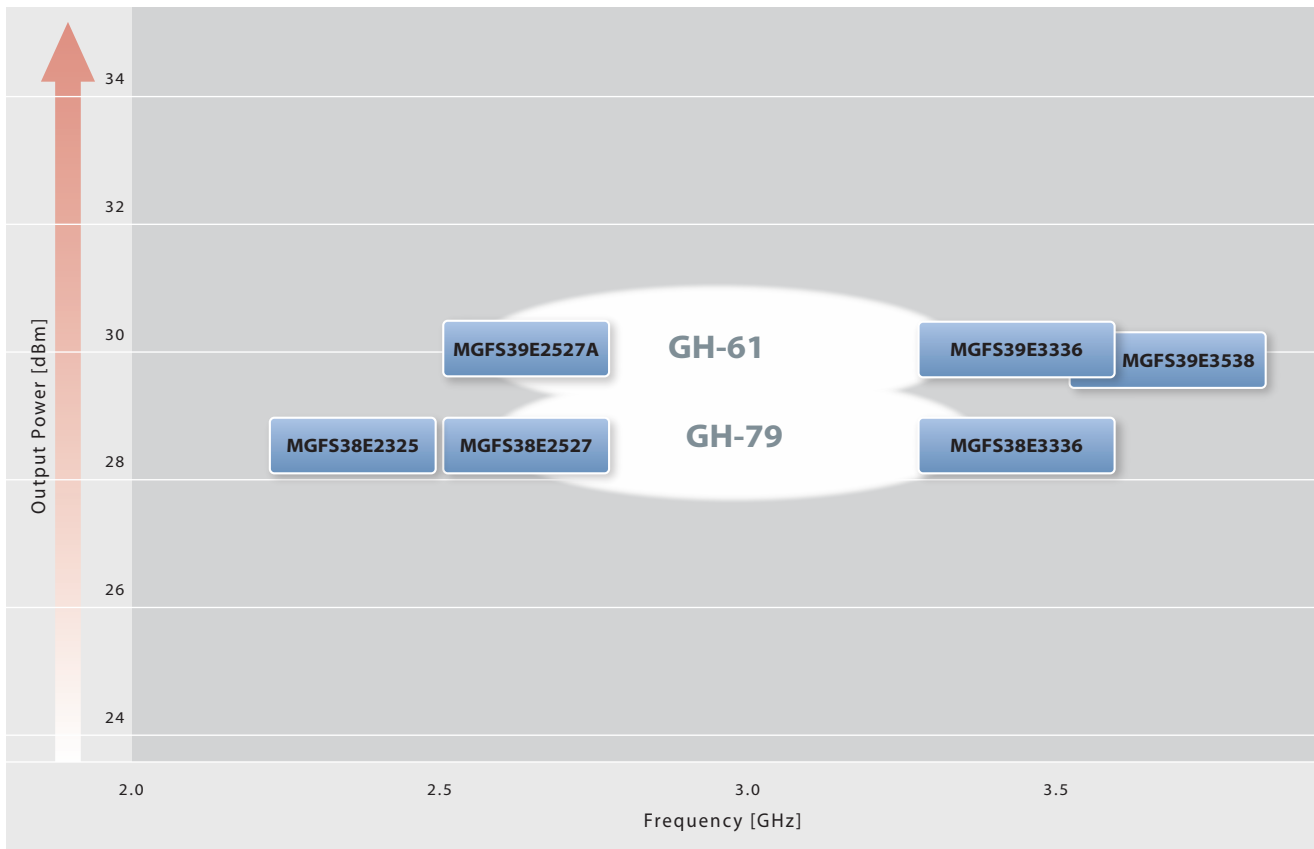
GaAs POWER AMPLIFIERS FOR MOBILE PHONE AND DATA COMMUNICATION



** : Under Development

LINE UP
SELECTION MAP
PRODUCT LIST
APPLICATION EXAMPLES

GaAs AMPLIFIERS FOR WiMAX / Wi-Fi



Type Name Definition of High Frequency Devices

GaAs FET/GaN HEMT (Discrete)

MGF 0951 P

A Plastic Mold : P
GaN : G

GaN HEMT (Internally Matched)

MGF C 50 G

A Freq. Band : C
B Typical Output power in dBm
C GaN : G

Internally Matched GaAs FET and GaAs Power Amplifier for WiMAX/Wi-Fi

MGF C 42 V 5964 A

A **B** **C** **D** **E**

A Freq. Band :
L, S, C, X, K, Ku

B Typical Output power in dBm
ex.36=36dBm=4W(typ.)

C Internally Matched : V, A, B
Multi Stage FET Amp : H
Multi Stage HBT Amp : E

D Freq. Band in GHz
ex.5964=5.9-6.4GHz
E Series Number

GaAs Power Amplifier

BA 01 2 D6

A **B** **C** **D**

A Device Structure : FA(FET), BA(Bipolar Transistor)

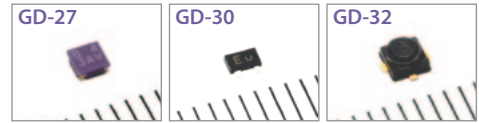
B Freq. Band in GHz

C Stage Number

D Series Number

PRODUCT LIST

GaAs FET/HEMT SERIES FOR MICROWAVE-BAND LOW-NOISE AMPLIFIERS



Type Number	Noise Figure [dB]		Associated Gain [dB]		Frequency [GHz]	Drain-Source Voltage [V]	Drain Current [mA]	Package Outline
	Typ.	Max.	Min.	Typ.				
MGF4941AL	0.35	0.50	12.0	13.5	12	2	10	GD-32
MGF4953A	0.40	0.50	12.0	13.0	12	2	10	GD-27
MGF4921AM	0.35	0.55	11.5	13.0	4	2	15	GD-30
MGF4931AM	0.60	0.80	10.0	11.5	12	2	7.5	GD-30
MGF4934BM	0.50	0.80	11.5	12.5	12	2	10	GD-30
MGF4934CM	0.50	0.75	11.5	13.0	12	2	10	GD-30
MGF4935AM	0.45	0.65	11.0	12.0	12	2	10	GD-30
MGF4936AM*	0.50	0.80	11.5	12.5	12	2	10	GD-30
MGF4953B	0.55	0.80	9.0	10.5	20	2	10	GD-27
MGF4963BL*	0.70	0.95	11.0	13.5	20	2	10	GD-32
MGF4964BL*	0.65	0.90	11.5	13.5	20	2	10	GD-32

Ta=25°C * : New Product

GaAs FET SERIES FOR MICROWAVE-BAND HIGH POWER AMPLIFIERS (Discrete Devices)



Type Number	Output Power at 1dB Gain Compression [dBm]		Output Power [dBm]	Linear Power Gain [dB]	3rd Order IM Distortion [dBc]		Power Added Efficiency [%]	Frequency [GHz]	Drain-Source Voltage [V]	Drain Current [A]	Thermal Resistance [°C/W]		Package Outline
	Min.	Typ.			Min.	Typ.					Typ.	Max.	
MGF0805A*	-	-	36.5	14.5	-	-	55	1.9	10	0.4	5	7	GF-50
MGF0904A	-	-	28	14	-	-	40	1.65	8	0.2	-	40	GF-7
MGF0905A	-	-	34	11	-	-	40	1.65	8	0.8	-	12.5	GF-7
MGF0906B^	35.5	37	-	11	-	-	40	2.3	10	1.2	-	6.5	GF-21
MGF0907B^	38.5	40	-	8	-	-	37	2.3	10	2.4	-	4	GF-21
MGF0909A	37	38	-	10	-	-	45	2.3	10	1.3	-	5	GF-7
MGF0910A^	37	38	-	10	-	-	37	2.3	10	1.3	-	6	GF-21
MGF0911A^	40	41	-	10	-	-	40	2.3	10	2.6	-	4.5	GF-21
MGF0913A	-	-	29.5	11	-	-	48	1.9	10	0.2	20	30	GF-50
MGF0915A	-	-	35	13	-	-	50	1.9	10	0.8	5	8	GF-50
MGF0918A	-	-	25	18	-	-	45	1.9	10	0.15	35	50	GF-50
MGF0920A	-	-	30	16	-	-	45	1.9	10	0.4	13	18	GF-50
MGF0921A	-	-	31	15	-	-	40	1.9	10	0.5	11	15	GF-50
MGF0951P	-	-	31	11	-	-42	50	2.15	10	0.2	20	25	GF-55
MGF0952P	-	-	36.5	11	-	-42	50	2.15	10	0.7	5	6	GF-55
MGF0953P	-	-	28	18	-	-	40	2.15	10	0.15	14	20	GF-55
MGF1451A^	11	13	-	10.5	-	-	-	12	3	0.03	-	-	GD-4
MGF1941AL*	11	13	-	9	-	-	-	12	3	0.03	-	-	GD-32
MGF1951A	11	13	-	7	-	-	-	12	3	0.03	-	-	GD-27
MGF1952A	15	17	-	5	-	-	-	12	3	0.06	-	-	GD-27
MGF1953A	18	20	-	4	-	-	-	12	4	0.1	-	-	GD-27
MGF1954A	21	23	-	3	-	-	-	12	6	0.1	-	-	GD-27
MGF2407A^	23	24.5	-	7	-	-	30	14.5	10	0.075	-	100	GF-17
MGF2415A^	26	27.5	-	6.5	-	-	29	14.5	10	0.15	-	60	GF-17
MGF2430A^	29	30.5	-	5.5	-	-	27	14.5	10	0.3	-	30	GF-17
MGF2445A^	31	32	-	5.5	-	-	20	12	10	0.45	-	15	GF-17
MGF4851A	12	14.5	-	9	-	-	-	12	2.5	0.025	-	-	GD-27

Ta=25°C ▲: Industrial grade * : New Product

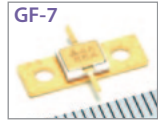
LINE UP

SELECTION MAP

PRODUCT LIST

APPLICATION EXAMPLES

GaN HEMT SERIES FOR MICROWAVE-BAND HIGH POWER AMPLIFIERS (Discrete Devices)



Type Number	Output Power at 3dB Gain Compression [dBm]		Output Power [dBm]	Linear Power Gain [dB]	3rd Order IM Distortion [dBc]		Drain Efficiency [%]	Frequency [GHz]	Drain-Source Voltage [V]	Drain Current [A]	Thermal Resistance [°C/W]		Package Outline
	Min.	Typ.			Min.	Typ.					Typ.	Max.	
MGF0840G*	39	40	-	14	-	-	60	2.6	47	0.09	5	-	GF-7
MGF0843G*	42	43	-	13	-	-	60	2.6	47	0.18	3	-	GF-7
MGF0846G*	45	46	-	12	-	-	60	2.6	47	0.35	2.2	-	GF-7

Ta=25°C * : New Product

GaN HEMT SERIES FOR SATELLITE COMMUNICATION (Internally Matched)



Type Number	Output Power at 3dB Gain Compression [dBm]		Output Power [dBm]	Linear Power Gain [dB]	3rd Order IM Distortion [dBc]		Power Added Efficiency [%]	Frequency [GHz]	Drain-Source Voltage [V]	Drain Current [A]	Thermal Resistance [°C/W]		Package Outline
	Min.	Typ.			Min.	Typ.					Typ.	Max.	
MGFC50G5867*	49	50	-	10	-	-	40	5.8~6.7	40	1.92	0.6	0.8	GF-38
MGFK47G3745**	-	-	47	9	-	-	30	13.75~14.5	24	1.05	-	-	GF-8

Ta=25°C * : New Product ** : Under Development

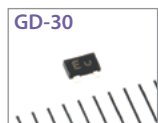
INTERNALLY MATCHED GaAs FET SERIES FOR WiMAX BASE STATION



Type Number	Output Power at 1dB Gain Compression [dBm]		Output Power [dBm]	Linear Power Gain [dB]	3rd Order IM Distortion [dBc]		Power Added Efficiency [%]	Frequency [GHz]	Drain-Source Voltage [V]	Drain Current [A]	Thermal Resistance [°C/W]		Package Outline
	Min.	Typ.			Min.	Typ.					Typ.	Max.	
MGFC36V3436	35	37	-	11	-42	-45	32	3.4~3.6	10	1.2	5	6	GF-8
MGFC39V3436	38	39.5	-	10	-42	-45	32	3.4~3.6	10	2.4	3	3.5	GF-8
MGFC42V3436	41.5	42.5	-	12	-42	-45	37	3.4~3.6	10	4.5	-	1.9	GF-18
MGFC45B3436B	-	-	45	11	-	-45	-	3.4~3.6	12	0.8	-	1.9	GF-60
MGFS45B2527B	-	-	45	12	-	-45	-	2.5~2.7	12	0.9	-	1.9	GF-60
MGFC47B3436B	-	-	47	10.5	-	-45	-	3.4~3.6	12	1.5	-	1.2	GF-60
MGFC47B3538B	-	-	47	10.5	-	-45	-	3.5~3.8	12	1.5	-	1.2	GF-60
MGFS45V2123A	44	45	-	12	-	-	45	2.1~2.3	10	6.5	1.25	1.5	GF-53
MGFS45V2325A	44	45	-	12	-	-	45	2.3~2.5	10	6.5	1.25	1.5	GF-53
MGFS45V2527A	44	45	-	12	-	-	45	2.5~2.7	10	6.5	1.25	1.5	GF-53
MGFS45V2735	44	45	-	12	-	-	45	2.5~2.7	10	6.5	0.8	1	GF-53

Ta=25°C

InGaP HBT SERIES FOR SATELLITE DIGITAL RADIOS

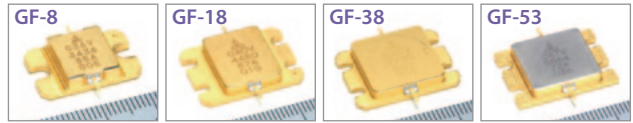


Type Number	Output Power at 1dB Gain Compression [dBm]		Output Power [dBm]	Linear Power Gain [dB]	3rd Order IM Distortion [dBc]		Power Added Efficiency [%]	Frequency [GHz]	Drain-Source Voltage [V]	Drain Current [A]	Thermal Resistance [°C/W]		Package Outline
	Min.	Typ.			Min.	Typ.					Typ.	Max.	
MGF3021AM*	-	11	-	22	-	24	-	2.4	3	14	-	-	GD-30
MGF3022AM*	-	16.5	-	18	-	32	-	2.4	3	33	-	-	GD-30

Ta=25°C * : New Product

PRODUCT LIST

INTERNALLY MATCHED GaAs FET SERIES FOR C BAND HIGH POWER AMPLIFIERS



Type Number	Output Power at 1dB Gain Compression [dBm]		Linear Power Gain [dB]	3rd Order IM Distortion [dBc]		Power Added Efficiency [%]	Frequency [GHz]	Drain-Source Voltage [V]	Drain Current [A]	Thermal Resistance [°C/W]		Package Outline
	Min.	Typ.		Min.	Typ.					Typ.	Max.	
MGFC36V4450A	35	37	9	-42	-45	32	4.4~5.0	10	1.2	5	6	GF-8
MGFC36V5258	35	36	9	-	-	33	5.2~5.8	10	1.2	-	6	GF-8
MGFC36V5964A	35	37	9	-42	-45	30	5.9~6.4	10	1.2	5	6	GF-8
MGFC36V6472A	35	37	8	-42	-45	30	6.4~7.2	10	1.2	5	6	GF-8
MGFC36V7177A	35	36.5	8	-42	-45	30	7.1~7.7	10	1.2	5	6	GF-8
MGFC39V3742A	38	39.5	9	-42	-45	31	3.7~4.2	10	2.4	-	3.5	GF-8
MGFC39V4450A	38	39	8	-42	-45	30	4.4~5.0	10	2.4	-	3.5	GF-8
MGFC39V5258	38	39	8	-	-	30	5.2~5.8	10	2.4	-	3.5	GF-8
MGFC39V5964A	38	39.5	8	-42	-45	30	5.9~6.4	10	2.4	-	3.5	GF-8
MGFC39V6472A	38	39.5	7	-42	-45	28	6.4~7.2	10	2.4	-	3.5	GF-8
MGFC39V7177A	38	39.5	7	-42	-45	28	7.1~7.7	10	2.4	-	3.5	GF-8
MGFC39V7785A	38	39.5	6	-42	-45	27	7.7~8.5	10	2.4	-	3.5	GF-8
MGFC40V3742	39.5	40.5	9	-42	-45	32	3.7~4.2	10	2.4	-	3.5	GF-18
MGFC40V4450	39.5	40.5	9	-42	-45	32	4.4~5.0	10	2.4	-	3.5	GF-18
MGFC40V5258	39.5	40.5	8	-	-	32	5.2~5.8	10	2.4	-	3.5	GF-18
MGFC40V5964	39.5	40.5	8	-42	-49	30	5.9~6.4	10	2.4	3	3.5	GF-18
MGFC40V6472	39.5	40.5	7	-42	-45	32	6.4~7.2	10	2.4	-	3.5	GF-18
MGFC40V7177	39	40	7	-42	-45	32	7.1~7.7	10	2.4	-	3.5	GF-18
MGFC42V3742	41.5	42.5	9	-42	-45	32	3.7~4.2	10	4.5	-	1.9	GF-38
MGFC42V4450	41.5	42.5	9	-42	-45	32	4.4~5.0	10	4.5	-	1.9	GF-18
MGFC42V5258	41.5	42.5	8	-	-	31	5.2~5.8	10	4.5	-	1.9	GF-18
MGFC42V5964A	41.5	42.5	8	-42	-45	33	5.9~6.4	10	4.5	-	1.6	GF-38
MGFC42V6472	41.5	42.5	7	-42	-45	30	6.4~7.2	10	4.5	-	1.9	GF-38
MGFC42V6472A	41.5	42.5	7	-42	-45	31	6.4~7.2	10	4.5	-	1.6	GF-38
MGFC42V7177	41	42	7	-42	-45	30	7.1~7.7	10	4.5	-	1.9	GF-38
MGFC42V7785A	41	42	6	-42	-45	28	7.7~8.5	10	4.5	-	1.6	GF-38
MGFC44V5964	43	44	8	-42	-	33	5.9~6.4	10	6.4	-	1.6	GF-38
MGFC44V6472	43	44	7	-42	-	31	6.4~7.2	10	6.4	-	1.6	GF-38
MGFC45V4450A	44	45	9	-42	-45	34	4.4~5.0	10	8	0.8	1	GF-38
MGFC45V5964A	44	45	8	-42	-45	33	5.9~6.4	10	8	0.8	1	GF-38
MGFC45V6472A	44.5	45	7	-42	-45	35	6.4~7.2	10	8	-	1	GF-38
MGFC47A4450	46	47	9.5	-	-	40	4.4~5.0	10	9.8	0.8	0.9	GF-53
MGFC47V5864	46	47	8.5	-	-	35	5.8~6.4	10	9.8	0.8	0.9	GF-53

Ta=25°C

INTERNALLY MATCHED GaAs FET SERIES FOR X/Ku BAND HIGH POWER AMPLIFIERS



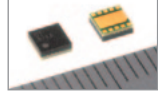
Type Number	Output Power at 1dB Gain Compression [dBm]		Linear Power Gain [dB]	3rd Order IM Distortion [dBc]		Power Added Efficiency [%]	Frequency [GHz]	Drain-Source Voltage [V]	Drain Current [A]	Thermal Resistance [°C/W]		Package Outline
	Min.	Typ.		Min.	Typ.					Typ.	Max.	
MGFK38A3745	37	38	7	-	-	30	13.75~14.5	10	1.5	3.6	4	GF-27
MGFK41A4045	40	41	6	-35	-	25	14.0~14.5	10	3	1.8	2.2	GF-8
MGFK44A4045	43	44	5	-35	-	17	14.0~14.5	10	6	1.2	1.5	GF-38
MGFX36V0717	34.5	36	8	-42	-	32	10.7~11.7	10	1.2	-	5.5	GF-27
MGFX39V0717	37.5	39	7	-42	-	26	10.7~11.7	10	2.4	-	3.5	GF-8

Ta=25°C

LINE UP
SELECTION MAP
PRODUCT LIST
APPLICATION EXAMPLES

GaAs HYBRID IC FOR MOBILE PHONE

BA012D6

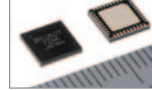


Type Number	Application	Frequency [MHz]	Po [dBm]	Vcc [V]	Vref [V]	PAE [%]	Pin [dBm]	Package Size
BA01266	CDMA2000	1920~1940	27.5	3.5	2.85	42	1.0	3×3×1.2mm ³
BA012B6	HSPA	824~849 1920~1980	26.5	3.5	2.9	40 43	-1.5 0.8	3×4.5×1mm ³
BA012G3	HSPA/LTE	824~849 1750~1785 1920~1980	26.5	3.5	2.9	38 42 41	-0.5 -1.0 0.0	3×4.5×1mm ³
BA012J1	HSPA/LTE	1920~1980	28.25	3.4	-	40	1.25	3×3×1mm ³
BA012J1C	HSPA/LTE/CDMA2000	1920~1980	28.25	3.4	-	37	1.25	3×3×1mm ³
BA012J2C	HSPA/LTE/CDMA2000	1850~1910	28.6	3.4	-	37	1.6	3×3×1mm ³
BA012J5C	HSPA/LTE/CDMA2000	815~849	28.25	3.4	-	37	1.25	3×3×1mm ³
BA012J8	HSPA/LTE	880~915	28.5	3.4	-	40	1.5	3×3×1mm ³
BA012D3	HSPA/LTE	1427.9~1462.9	28.5	3.4	-	40	0.5	3×3×1mm ³
BA012K7**	HSPA/LTE	1427.9~1462.9	28.5	3.4	-	40	0.5	3×3×1mm ³
BA012D6	HSPA/LTE	1710~1785	28.4	3.4	-	40	1.4	3×3×1mm ³

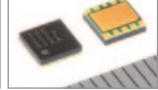
** : Under Development

GaAs AMPLIFIER FOR WIMAX / Wi-Fi

GH-61



GH-79



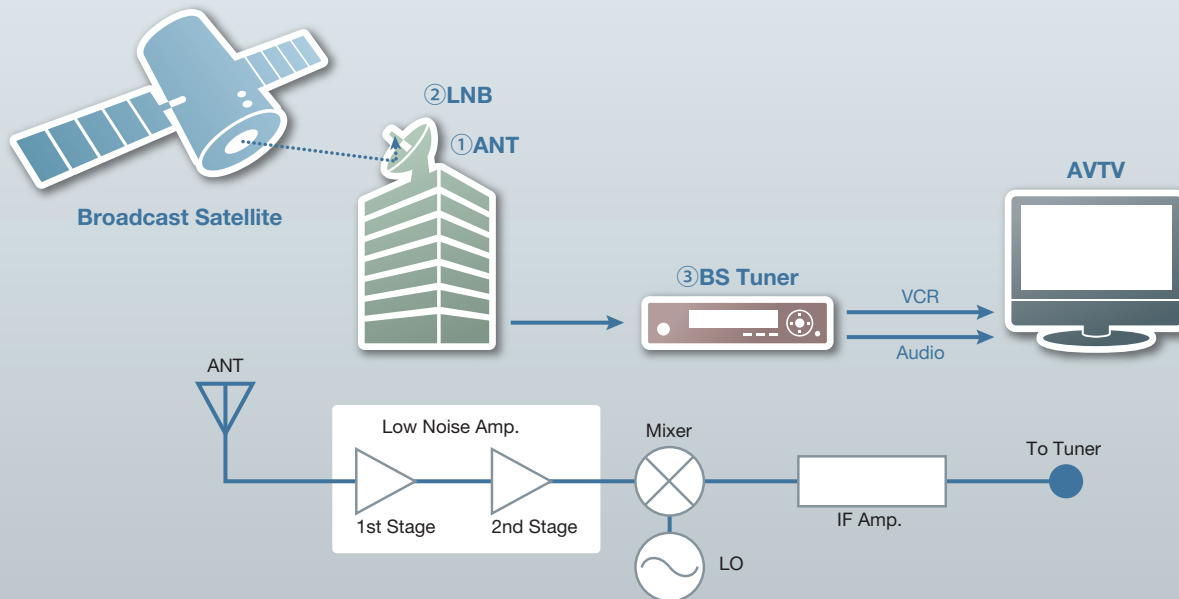
Type Number	Frequency [GHz]	Pout & EVM	Gain [dB]	Vcc [V]	Vref [V]	PAE [%]	Package Outline
MGFS39E2527A	2.5~2.7 (2.3~2.5)	30dBm@2.5%	43	6	2.85	14	GH-61
MGFS39E3336	3.3~3.6	30dBm@2.5%	43	6	2.85	14	GH-61
MGFS39E3538*	3.5~3.8	30dBm@2.5%	39	6	2.85	14	GH-61
MGFS38E2325*	2.3~2.5	28.5dBm@2.5%	36	5	2.85	15	GH-79
MGFS38E2527*	2.5~2.7	28.5dBm@2.5%	36	5	2.85	15	GH-79
MGFS38E3336*	3.3~3.6	28.5dBm@2.5%	35	5	2.85	15	GH-79

* : New Product

All Products Here Are RoHS Compliant

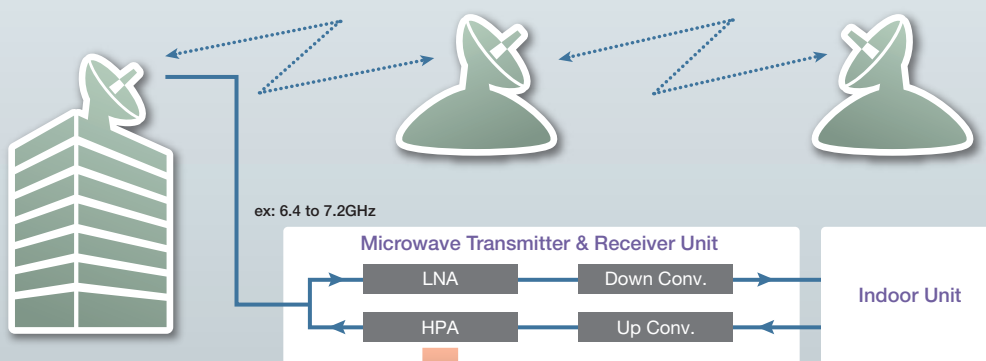
APPLICATION EXAMPLES

Lineup for 12GHz -Band LNB



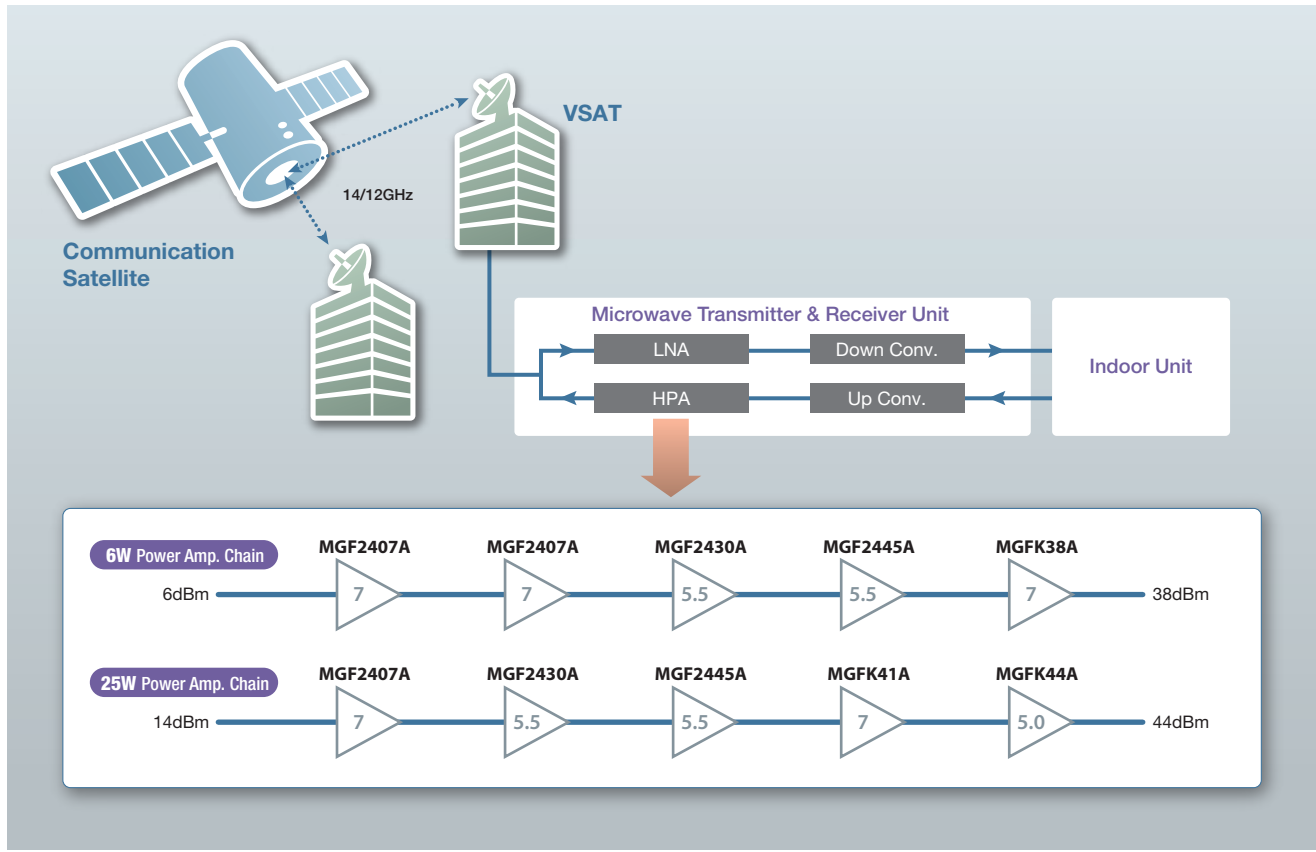
Performance of LNB	1st Stage	2nd Stage	Mixer
Low Noise Model	MGF4941AL	MGF4941AL	MGF4934CM
Standard Model	MGF4935AM	MGF4934CM	MGF4934CM

Lineup for Microwave Links

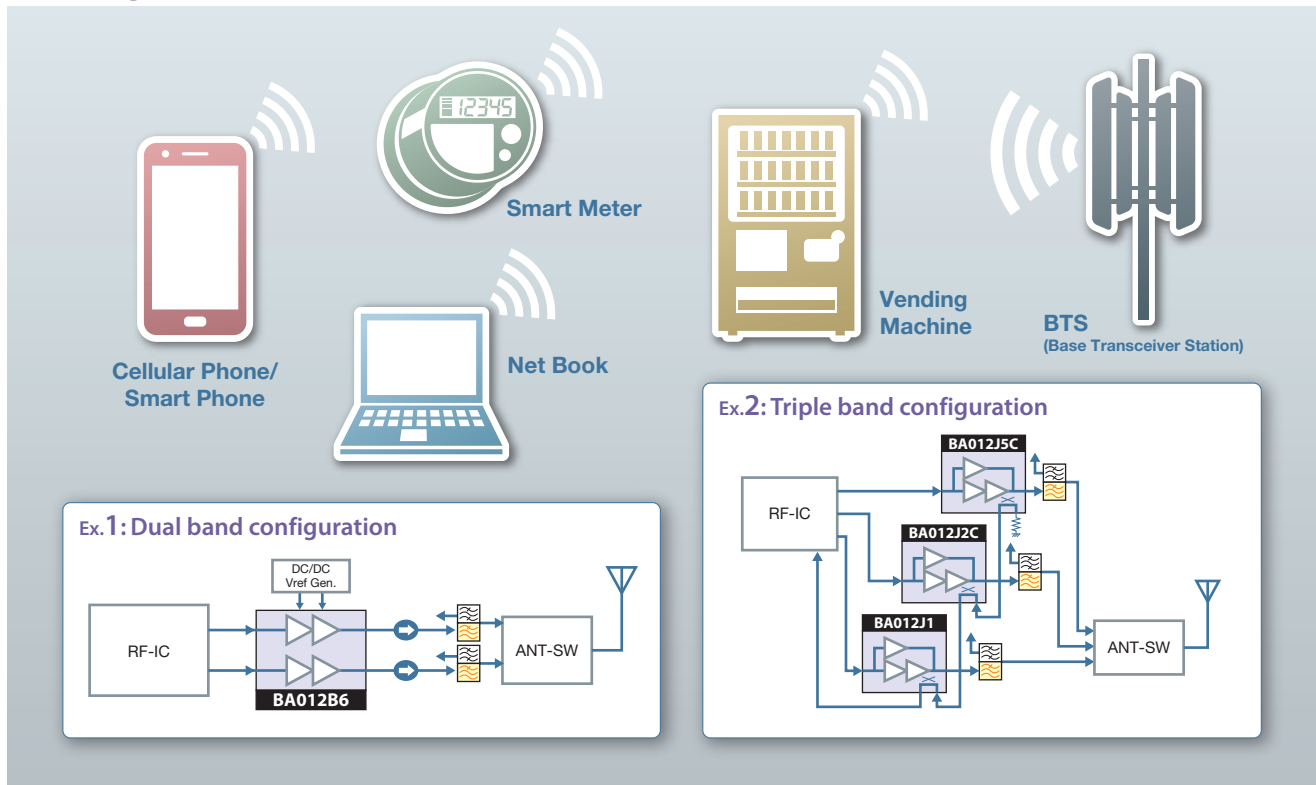


30W Power Amp. Chain	MGF1951A	MGF2407A	MGF2445A	MGFC39V	MGFC45V	45dBm
	13	11	9	7	6.5	
50W Power Amp. Chain	MGF1951A	MGF2407A	MGF2445A	MGFC42V	MGFC47A	47dBm
	13	11	9	8	7	

Lineup for Satellite Communication



GaAs Hybrid IC for Mobile Phone Tx block configuration for mobile phone



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